




ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	High-Density connection between multiple circuit boards						
Application Number: 10/813945							
Confirmation Number: 5777							
First Named Applicant: Douglas Wildes							
Attorney Docket Number: 134730							
Search string:				(6520789 or 6437557 or 6309223 or 6162065 or 5871362 or 5378161).pn.			
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6520789	2003-02-18	Daughert, Jr. et al.		439	329
	2	6437557	2002-08-20	Smith		324	158.1
	3	6309223	2001-10-30	Wolfe		439	67
	4	6162065	2000-12-19	Benham		439	67
	5	5871362	1999-02-16	Campbell et al.		439	67
	6	5378161	1995-01-03	Loder		439	77
Signature							
Examiner Name				Date			
Michael C. Zanolis				4/7/05			

UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Douglas G. Wildes et al. : Group Art Unit:
Serial No.: To Be Assigned : Examiner: ²⁸³⁹
Filed: Concurrently *Zarrol*
Title: HIGH-DENSITY CONNECTION BETWEEN
MULTIPLE CIRCUIT BOARDS

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB- CLASS	FILING DATE
<i>MCZ</i>	A	5,160,269	11/3/92	Fox, Jr. et al.	439	67	
	B	6,007,490	12/28/99	Pawluskiewicz	600	459	
<i>↓</i>	C	6,017,244	1/25/00	Daane	439	495	

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATIONS

EXAM- INER INITIAL		PUB. NUMBER	PUBLI- CATION DATE	COUNTRY OR PATENT OFFICE	CLASS	SUB- CLASS	TRANS- LATION	
							YES	NO

OTHER DOCUMENTS

(Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner: <i>Richard C. Zarrol</i>	Date Considered: <i>4/7/05</i>
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.